



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN#20191101000.1A**

**Qualification of CDAT as an additional assembly site for select QFN devices  
Change Notification / Sample Request**

**Date:** December 27, 2019

**To:** TOKYO ELECTRON DEVICE (DSTR) PCN

**Revision A** is to update/correct the Assembly city reference in the Changes to product identification resulting from the PCN section.

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team ([PCN ww admin team@list.ti.com](mailto:PCN_admin_team@list.ti.com)). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team  
SC Business Services

**20191101000.1A**  
**Change Notification / Sample Request**  
**Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TPS63001DRCR	null
TPS63001DRCT	null
TPS74801RGWT	null
TPS74901RGWT	null
SN74AVC8T245RHLL	null
TPS2113ADRB	null
TPS51916RUKT	null
TPS63002DRCT	null
TPS74801DRCT	null
TPS2115ADRB	null
TPS62162DSGR	null
TPS62172DSGT	null
TPS63000DRCT	null
TPS74801DRCR	null
TPS63000DRCR	null
TPS74801RGWR	null
TPS62172DSGR	null
TPS74901RGWR	null
TPS2113ADRB	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20191101000.1A			<b>PCN Date:</b>	Dec. 27 2019																																											
<b>Title:</b>	Qualification of CDAT as an additional assembly site for select QFN devices																																															
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services																																													
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Feb 22 2020		<b>Estimated Sample Availability:</b>	Date provided at sample request																																												
<b>Change Type:</b>																																																
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site																																											
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material																																											
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process																																											
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site																																											
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials																																											
				<input type="checkbox"/>	Wafer Fab Process																																											
<b>PCN Details</b>																																																
<b>Description of Change:</b>																																																
<p><b>Revision A</b> is to update/correct the Assembly city reference in the Changes to product identification resulting from the PCN section.</p> <p>Texas Instruments is pleased to announce the qualification of CDAT as an additional assembly site for the list of QFN devices shown below. Current assembly sites and Material differences are as follows:</p> <p><b>Group 1 BOM comparison:</b></p> <table border="1"> <thead> <tr> <th></th> <th>MLA</th> <th>CDAT</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>4208625</td> <td><a href="#">4222198</a></td> </tr> <tr> <td>Mount Compound</td> <td>4205846</td> <td><a href="#">4207123</a></td> </tr> </tbody> </table> <p><b>Group 2 BOM comparison:</b></p> <table border="1"> <thead> <tr> <th></th> <th>MLA</th> <th>Clark</th> <th>CDAT</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>4208625</td> <td>4208625</td> <td><a href="#">4222198</a></td> </tr> <tr> <td>Mount Compound</td> <td>4205846</td> <td>4207768</td> <td><a href="#">4207123</a></td> </tr> </tbody> </table> <p><b>Group 3 BOM comparison:</b></p> <table border="1"> <thead> <tr> <th></th> <th>MLA</th> <th>CDAT</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>4208625</td> <td><a href="#">4222198</a></td> </tr> <tr> <td>Mount Compound</td> <td>4212088</td> <td><a href="#">4207123</a></td> </tr> </tbody> </table> <p><b>Group 4 BOM comparison:</b></p> <table border="1"> <thead> <tr> <th></th> <th>MLA</th> <th>CDAT</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>4208625</td> <td><a href="#">4222198</a></td> </tr> <tr> <td>Mount Compound</td> <td>4207768</td> <td><a href="#">4207123</a></td> </tr> </tbody> </table> <p><b>Reason for Change:</b></p> <p>Continuity of Supply</p> <p><b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b></p> <p>None</p> <p><b>Anticipated impact on Material Declaration</b></p> <table border="1"> <tr> <td><input type="checkbox"/></td> <td>No Impact to the Material Declaration</td> <td><input checked="" type="checkbox"/></td> <td>Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a></td> </tr> </table>							MLA	CDAT	Mold Compound	4208625	<a href="#">4222198</a>	Mount Compound	4205846	<a href="#">4207123</a>		MLA	Clark	CDAT	Mold Compound	4208625	4208625	<a href="#">4222198</a>	Mount Compound	4205846	4207768	<a href="#">4207123</a>		MLA	CDAT	Mold Compound	4208625	<a href="#">4222198</a>	Mount Compound	4212088	<a href="#">4207123</a>		MLA	CDAT	Mold Compound	4208625	<a href="#">4222198</a>	Mount Compound	4207768	<a href="#">4207123</a>	<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a>
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### Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
MLA	MLA	MYS	Chengdu <b>Kuala Lumpur</b>
CLARK	QAB	PHL	Angeles City, Pampanga
<b>CDAT</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>

Sample product shipping label (not actual product label)



### Product Affected:

#### Group 1 Device List (Current MLA Assembly, add CDAT):

74AVC8T245RHRLRG4	TPS2115ADRBR	TPS63000DRCR	TPS63001DRCRG4
HPA00720RHLR	TPS2115ADRBT	TPS63000DRCRG4	TPS63001DRCT
SN74AVC8T245RHRLR	TPS2115ADRBGT4	TPS63000DRCT	TPS63002DRCR
TPS2113ADRBR	TPS53321RGTR	TPS63000DRCTG4	TPS63002DRCT
TPS2113ADRBT	TPS53321RGTT	TPS63001DRCR	TPS63002DRCTG4

#### Group 2 Device List (Current MLA Assembly & Clark, add CDAT):

TPS74801DRCR	TPS74801RGWR	TPS74801RGWTG4	TPS74901RGWR
TPS74801DRCRG4	TPS74801RGWRG4	TPS74901DRCR	TPS74901RGWT
TPS74801DRCT	TPS74801RGWT	TPS74901DRCT	TPS74901RGWTG4
TPS74801DRCTG4			

#### Group 3 Device List (Current MLA Assembly, add CDAT):

TPS62162DSGR	TPS62162DSGT	TPS62172DSGR	TPS62172DSGT
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#### Group 4 Device List (Current MLA Assembly, add CDAT):

SN1409030RUKR	TPS51916RUKR	TPS51916RUKT
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## Group 1 Qual Memo:



TI Information  
Selective Disclosure

### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: E58T245RHLR	QBS Package Reference: BQ24196RGER	QBS Package Reference: BQ29200DRBR	QBS Package Reference: SN74AXC8T245RHLR	QBS Package Reference: TPS3850G09DRC	QBS Package Reference: TPS62140RGTR	QBS Package Reference: TRS3122ERGER	QBS Package Reference: UCC27282DRC
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	-	3/231/0	3/231/0	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-	Pass	Pass	Pass	Pass	Pass
FLAM	Flammability (IEC 695-2-2)	--							3/15/0	
FLAM	Flammability (UL 94V-0)	--							3/15/0	
FLAM	Flammability (UL-1694)	--							3/15/0	
HAST	Biased HAST, 110C/85%RH	26 Hours	-	-	-	-	-	-	-	1/77/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	3/231/0	2/154/0
HTOL	Life Test, 140C	480 Hours	-	-	-	-	-	-	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	-	-	-	1/77/0	-	1/77/0	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	3/231/0	-	-	3/231/0	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	3/231/0	-	-	-
SD	Surface Mount Solderability	Pb Free							1/22/0	
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	3/231/0	-	-	-	-
WBP	Bond Pull	Wires	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0

- QBS: Qual By Similarity  
- Qual Device E58T245RHLR is qualified at LEVEL1-260CG  
- Preconditioning was performed for Auto clave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable  
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours  
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours  
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**  
Qualified Pb-Free(SMT) and Green

## Group 2 Qual Memo:



TI Information  
Selective Disclosure

### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS74801DRCR	QBS Package Reference: 430F2132IRHBR	QBS Package Reference: BQ24196RGER	QBS Package Reference: BQ294504DRVR	QBS Package Reference: TPS51285BRUKR	QBS Package Reference: TRS3122ERGER
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-	-	-	Pass
FLAM	Flammability (IEC 695- 2-2)	--	-	-	-	-	-	3/15/0
FLAM	Flammability (UL 94V- 0)	--	-	-	-	-	-	3/15/0
FLAM	Flammability (UL-1694)	--	-	-	-	-	-	3/15/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	-	-	-	-	1/77/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	-	-	3/231/0
SD	Surface Mount Solderability	Pb Free	-	-	-	-	-	1/22/0
TC	Temperature Cycle, - 65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
WBP	Bond Pull	Wires	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0

- QBS: Qual By Similarity  
- Qual Device TPS74801DRCR is qualified at LEVEL2-260C  
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable  
- The following are equivalent HTOL options based on activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours  
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours  
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
**Green/Pb-free Status:**  
Qualified Pb-Free(SMT) and Green

## Group 3 Qual Memo:



TI Information  
Selective Disclosure

### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <a href="#">TPS62162DSGR</a>	QBS Package Reference: <a href="#">BQ294504DRVR</a>	QBS Package Reference: <a href="#">QPA2170AIDSGR</a>	QBS Package Reference: <a href="#">TPS53605DSQ</a>	QBS Package Reference: <a href="#">TRS3122ERGER</a>
-	CLHTOL (FF)	125C (1000 Hours), Abs Max (36V)	-	-	-	1/47/0	-
-	CLHTOL (FS)	125C (1000 Hours), Abs Max (36V)	-	-	-	1/33/0	-
-	CLHTOL (SF)	125C (1000 Hours), Abs Max (36V)	-	-	-	1/33/0	-
-	CLHTOL (SS)	125C (1000 Hours), Abs Max (36V)	-	-	-	1/47/0	-
-	Moisture Sensitivity Level, JEDEC	Level 2-260C	3/36/0	-	-	-	-
AC	Autoclave 121C	192 Hours	-	3/231/0	-	-	-
AC	Autoclave 121C	96 Hours	-	3/231/0	-	-	3/231/0
CDM	ESD - CDM	1000 V	-	-	3/9/0	3/9/0	-
CDM	ESD - CDM	1500 V	-	-	2/6/0	2/6/0	1/3/0
CDM	ESD - CDM	250 V	-	-	3/9/0	3/9/0	-
CDM	ESD - CDM	500 V	-	-	3/9/0	3/9/0	-
CDM	ESD - CDM	750 V	-	-	3/9/0	3/9/0	-
DS	Die Shear	QSS 009-009	-	-	-	-	3/30/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	1/Pass	3/90/0	1/30/0
ED	Electrical Characterization, side by side	-	1/Pass	-	-	-	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	3/2999/0	-
FLAM	Flammability (IEC 695-2-2)	--	-	-	-	-	3/15/0
FLAM	Flammability (UL 94V-0)	--	-	-	-	-	3/15/0
FLAM	Flammability (UL-1694)	--	-	-	-	-	3/15/0
HAST	Biased HAST, 110C/85%RH	264 Hours	-	-	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	192 Hours	-	3/228/0	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	3/231/0
HBM	ESD - HBM	1000 V	-	-	3/9/0	3/9/0	-
HBM	ESD - HBM	1500 V	-	-	3/9/0	3/9/0	-

Type	Test Name / Condition	Duration	Qual Device: TPS62162DSGR	QBS Package Reference: BQ294504DRVR	QBS Package Reference: OPA2170AIDSGR	QBS Package Reference: TPS53605DSQ	QBS Package Reference: TRS3122ERGER
HBM	ESD - HBM	2000 V	-	-	3/9/0	3/9/0	-
HBM	ESD - HBM	2500 V	-	-	-	3/9/0	-
HBM	ESD - HBM	3000 V	-	-	3/9/0	-	-
HBM	ESD - HBM	4000 V	-	-	3/9/0	-	1/3/0
HBM	ESD - HBM	500 V	-	-	3/9/0	2/6/0	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	3/231/0	-
HTOL	Life Test, 150C	300 Hours	-	-	-	-	1/77/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0	2/90/0	-
LU	Latch-up	(per JESD78)	-	-	-	-	1/6/0
LU	Latch-up	Latchup/125C	-	-	-	3/18/0	-
LU	Latch-up	Latchup/25c	-	-	1/6/0	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/Pass	3/Pass	-	3/Pass	3/Pass
MQ	Manufacturability (Assembly)	(per mfg. Site specification) Request crater check	-	-	3/Pass	-	-
MQ	Manufacturability (Testability - TQ)	(per mfg. Site specification)	-	-	-	-	1/Pass
MSL	Thermal Path Integrity	Level 1-260C	-	3/36/0	-	-	-
MSL	Thermal Path Integrity	Level 2-260C	-	-	-	-	3/36/0
MSL	Thermal Path Integrity, JEDEC, L2	Elec-2/25C	-	-	1/12/0	-	-
MSL	Thermal Path Integrity, JEDEC, L2	Level 2	-	-	2/24/0	-	-
PC	PreCon Level 2	Elec/25C	-	-	3/1249/0	11/815/0	-
PC	PreCon Level 2	Level 2-260C	-	-	-	-	3/1005/0
PD	Physical Dimensions	(per mechanical drawing)	-	-	1/5/0	3/90/0	3/30/0
SD	Pb Free Solderability	Pb Free/Solderability	-	-	-	3/15/0	-
SD	Surface Mount Solderability	Pb Free	-	-	-	-	1/22/0
TC	Temperature Cycle, - 65/150C	1000 Cycles	-	3/231/0	-	-	-
TC	Temperature Cycle, - 65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, - 65/150C	750 Cycles	-	3/231/0	3/231/0	-	-
UHASt	Unbiased HAST 110C/85%RH	264 Hours	-	-	-	3/231/0	-
UHASt	Unbiased HAST 130C/85%RH	96 Hours	-	-	3/231/0	-	-

Type	Test Name / Condition	Duration	Qual Device: TPS62162DSGR	QBS Package Reference: BQ294504DRVR	QBS Package Reference: OPA2170AIDSGR	QBS Package Reference: TPS53605DSQ	QBS Package Reference: TRS3122ERGER
VM	Visual / Mechanical	(per mfg. Site specification)	-	-	-	-	3/984/0
VM	Visual Quality Reliability Inspection	Post 1000 Cycles Temp Cycle	-	3/6/0	-	-	-
VM	Visual Quality Reliability Inspection	Post 192 Hours HAST	-	3/6/0	-	-	-
VM	Visual Quality Reliability Inspection	Post 96 Hours HAST	-	3/6/0	-	-	-
VM	Visual Quality Reliability Inspection	Post Autoclave	-	-	-	-	3/Pass
VM	Visual Quality Reliability Inspection	Post Temp Cycle	-	-	-	-	3/Pass
WBP	Bond Pull	36 leads, 5 units/lot	-	-	-	3/228/0	-
WBP	Bond Pull	76 Wire, 3 units min	-	-	-	-	3/228/0
WBP	Bond Pull	Wires	3/228/0	3/228/0	-	-	-
WBS	Ball Bond Shear	36 leads, 5 units/lot	-	-	-	3/228/0	-
WBS	Ball Bond Shear	76 balls, 3 units min	-	-	-	-	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0	-	-	-
XRAY	X-ray	(top side only)	-	-	-	-	3/15/0

- QBS: Qual By Similarity

- Qual Device TPS62162DSGR is qualified at LEVEL2-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JEDEC47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green



## Group 4 Qual Memo:



TI Information  
Selective Disclosure

### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS51916RUKR	QBS Package Reference: BQ294504DRV	QBS Package Reference: TPS51285BRUKR	QBS Package Reference: TPS53605DSQ	QBS Package Reference: TRS3122ERGER
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-	Pass	Pass
FLAM	Flammability (IEC 695-2-2)	--	-	-	-	-	3/15/0
FLAM	Flammability (UL 94V-0)	--	-	-	-	-	3/15/0
FLAM	Flammability (UL-1694)	--	-	-	-	-	3/15/0
HAST	Biased HAST, 110C/85%RH	264 Hours	-	-	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	-	3/231/0
HTOL	Life Test, 125C	1000 Hours	-	-	-	3/231/0	-
HTOL	Life Test, 150C	300 Hours	-	-	-	-	1/77/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	2/90/0	3/231/0
SD	Pb Free Solderability	Pb Free/Solderability	-	-	-	3/15/0	1/22/0
TC	Temperature Cycle, - 65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0	3/231/0
UHA	Unbiased HAST 110C/85%RH	264 Hours	-	-	-	3/231/0	-
WBP	Bond Pull	Wires	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0	3/228/0	3/228/0	3/228/0

- QBS: Qual By Similarity  
- Qual Device TPS51916RUKR is qualified at LEVEL2-260CG  
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable  
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours  
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours  
- The following are equivalent Temp Cycle options per JEDEC47: -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
**Green/Pb-free Status:**  
Qualified Pb-Free(SMT) and Green

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